

RF Power Field Effect Transistor

N-Channel Enhancement-Mode Lateral MOSFET

Designed for GSM and GSM EDGE base station applications with frequencies from 1.8 to 2.0 GHz. Suitable for FM, TDMA, CDMA and multicarrier amplifier applications. To be used in Class AB for GSM and GSM EDGE cellular radio applications.

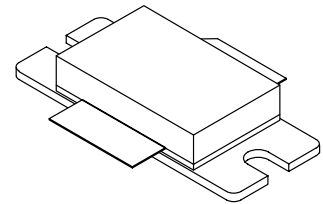
- GSM and GSM EDGE Performances, Full Frequency Band
Power Gain — 13.5 dB (Typ) @ 90 Watts CW
Efficiency — 52% (Typ) @ 90 Watts CW
- Capable of Handling 10:1 VSWR, @ 26 Vdc, 90 Watts CW Output Power

Features

- Internally Matched for Ease of Use
- High Gain, High Efficiency and High Linearity
- Integrated ESD Protection
- Designed for Maximum Gain and Insertion Phase Flatness
- Excellent Thermal Stability
- Characterized with Series Equivalent Large-Signal Impedance Parameters
- RoHS Compliant
- In Tape and Reel. R3 Suffix = 250 Units per 56 mm, 13 inch Reel.

MRF18090AR3

**1.80-1.88 GHz, 90 W, 26 V
LATERAL N-CHANNEL
RF POWER MOSFET**



**CASE 465B-03, STYLE 1
NI-880**

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DS}	-0.5, +65	Vdc
Gate-Source Voltage	V_{GS}	-0.5, +15	Vdc
Total Device Dissipation @ $T_C = 25^\circ\text{C}$ Derate above 25°C	P_D	250 1.43	W W/ $^\circ\text{C}$
Storage Temperature Range	T_{stg}	- 65 to +150	$^\circ\text{C}$
Case Operating Temperature	T_C	150	$^\circ\text{C}$
Operating Junction Temperature	T_J	200	$^\circ\text{C}$

Table 2. Thermal Characteristics

Characteristic	Symbol	Value	Unit
Thermal Resistance, Junction to Case	$R_{\theta JC}$	0.7	$^\circ\text{C}/\text{W}$

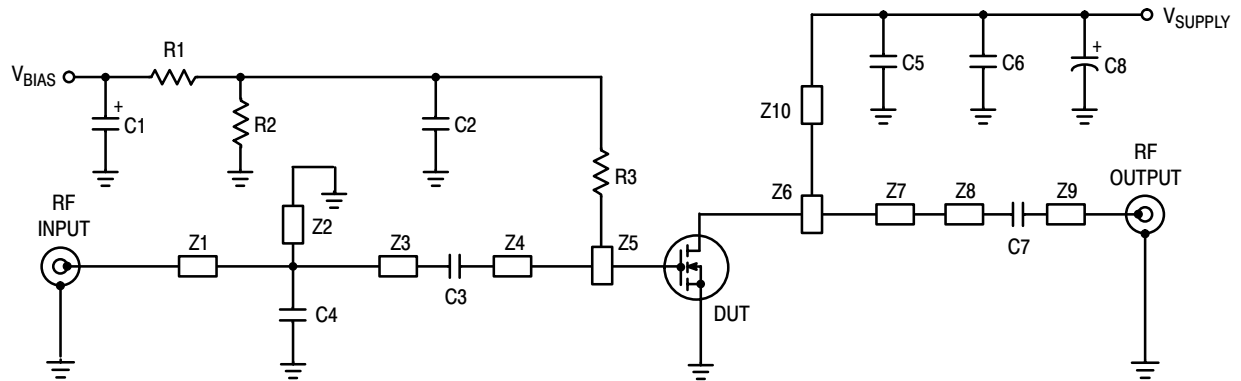
Table 3. ESD Protection Characteristics

Test Conditions	Class
Human Body Model	2 (Minimum)
Machine Model	M3 (Minimum)

Table 4. Electrical Characteristics ($T_C = 25^\circ\text{C}$ unless otherwise noted)

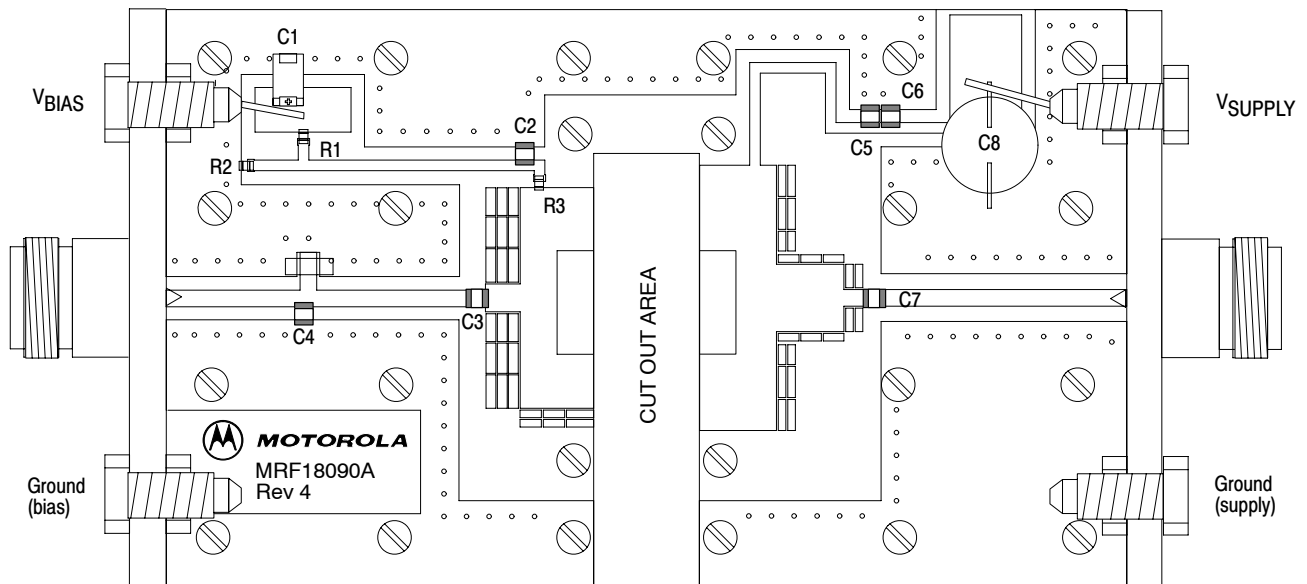
Characteristic	Symbol	Min	Typ	Max	Unit
Off Characteristics					
Drain-Source Breakdown Voltage ($V_{GS} = 0\text{ Vdc}$, $I_D = 100\text{ }\mu\text{Adc}$)	$V_{(BR)DSS}$	65	—	—	Vdc
Zero Gate Voltage Drain Current ($V_{DS} = 26\text{ Vdc}$, $V_{GS} = 0\text{ Vdc}$)	I_{DSS}	—	—	10	μAdc
Gate-Source Leakage Current ($V_{GS} = 5\text{ Vdc}$, $V_{DS} = 0\text{ Vdc}$)	I_{GSS}	—	—	1	μAdc
On Characteristics					
Gate Quiescent Voltage ($V_{DS} = 26\text{ Vdc}$, $I_D = 750\text{ mAdc}$)	$V_{GS(Q)}$	2.5	3.7	4.5	Vdc
Drain-Source On-Voltage ($V_{GS} = 10\text{ Vdc}$, $I_D = 1\text{ Adc}$)	$V_{DS(on)}$	—	0.1	—	Vdc
Forward Transconductance ($V_{DS} = 10\text{ Vdc}$, $I_D = 3\text{ Adc}$)	g_{fs}	—	7.2	—	S
Dynamic Characteristics					
Reverse Transfer Capacitance ($V_{DS} = 26\text{ Vdc} \pm 30\text{ mV(rms)ac}$ @ 1 MHz, $V_{GS} = 0\text{ Vdc}$)	C_{rss}	—	4.2	—	pF
Functional Tests (In Freescale Test Fixture)					
Common-Source Amplifier Power Gain @ 90 W ⁽¹⁾ ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 750\text{ mA}$, $f = 1805 - 1880\text{ MHz}$)	G_{ps}	12.0	13.5	—	dB
Drain Efficiency @ 90 W ⁽¹⁾ ($V_{DD} = 26\text{ Vdc}$, $I_{DQ} = 750\text{ mA}$, $f = 1805 - 1880\text{ MHz}$)	η	47	52	—	%
Input Return Loss ⁽¹⁾ ($V_{DD} = 26\text{ Vdc}$, $P_{out} = 90\text{ W CW}$, $I_{DQ} = 750\text{ mA}$, $f = 1805 - 1880\text{ MHz}$)	IRL	—	—	-10	dB

1. To meet application requirements, Freescale test fixtures have been designed to cover the full GSM1800 band, ensuring batch-to-batch consistency.



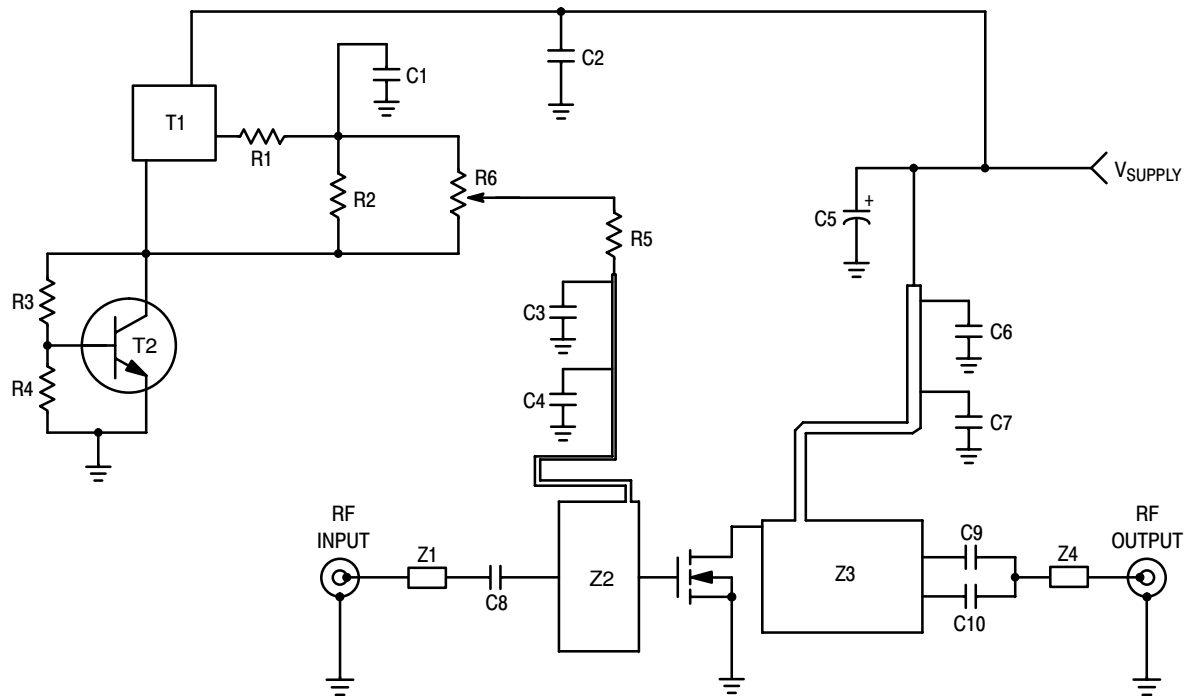
C1	10 μ F, 35 V Tantalum Capacitor, Vishay-Sprague #293D106X9035D	Z3	0.819" x 0.087" Microstrip
C2, C3	10 pF, 100B Chip Capacitor , ATC #100B100GW	Z4	0.181" x 0.144" Microstrip
C4	3.3 pF, 100B Chip Capacitor, ATC #100B3R3BW	Z5	0.383" x 1.148" Microstrip
C5, C6	6.8 pF, 100B Chip Capacitors, ATC #100B6R8CW	Z6	0.400" x 1.380" Microstrip
C7	12 pF, 100B Chip Capacitors, ATC #100B120GW	Z7	0.351" x 0.351" Microstrip
C8	220 μ F, 63 V Electrolytic Capacitor, Philips #13668221	Z8	0.126" x 0.087" Microstrip
R1, R2	10 k Ω , 1/8 W Chip Resistors (0805)	Z9	1.280" x 0.087" Microstrip
R3	1.0 k Ω , 1/8 W Chip Resistor (0805)	Z10	$\approx$ 1.275" x 0.055" Microstrip
Z1	0.697" x 0.087" Microstrip	PCB	Taconic TLX8-0300, 0.030", $\epsilon_r = 2.55$
Z2	0.087" x 0.197" Microstrip		

Figure 1. MRF18090A 1.80 - 1.88 GHz Test Fixture Schematic



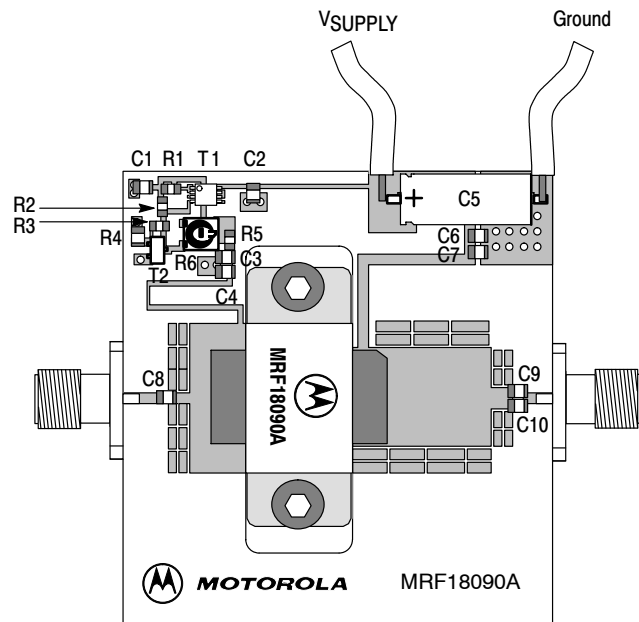
Freescall has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescall Semiconductor signature/logo. PCBs may have either Motorola or Freescall markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 2. MRF18090A 1.80 - 1.88 GHz Test Fixture Component Layout



C1, C3	1 μ F Chip Capacitors (0805)	R5	10 k Ω Chip Resistor (0603)
C2	0.1 μ F Chip Capacitor (0805)	R6	5 k Ω , SMD Potentiometer
C4	1 nF Chip Capacitor (0805)	T1	LP2951 Micro-8 Voltage Regulator
C5	220 μ F, 50 V Electrolytic Capacitor	T2	BC847 SOT-23 NPN Transistor
C6, C7	8.2 pF, 100A Chip Capacitors	Z1	0.210" x 0.055" Microstrip
C8, C9, C10	22 pF, 100A Chip Capacitors	Z2	0.419" x 0.787" Microstrip
R1	10 Ω Chip Resistor (0805)	Z3	0.836" x 0.512" Microstrip
R2, R3	1 k Ω Chip Resistors (0805)	Z4	0.164" x 0.055" Microstrip
R4	2.2 k Ω Chip Resistor (0805)	Substrate = 0.5 mm Teflon [®] Glass	

Figure 3. 1.80 - 1.88 GHz Demo Board Schematic



Freescale has begun the transition of marking Printed Circuit Boards (PCBs) with the Freescale Semiconductor signature/logo. PCBs may have either Motorola or Freescale markings during the transition period. These changes will have no impact on form, fit or function of the current product.

Figure 4. 1.80 - 1.88 GHz Demo Board Component Layout

TYPICAL CHARACTERISTICS

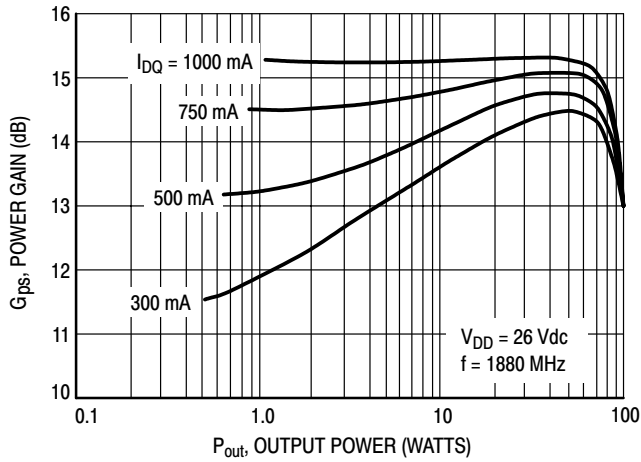


Figure 5. Power Gain versus Output Power

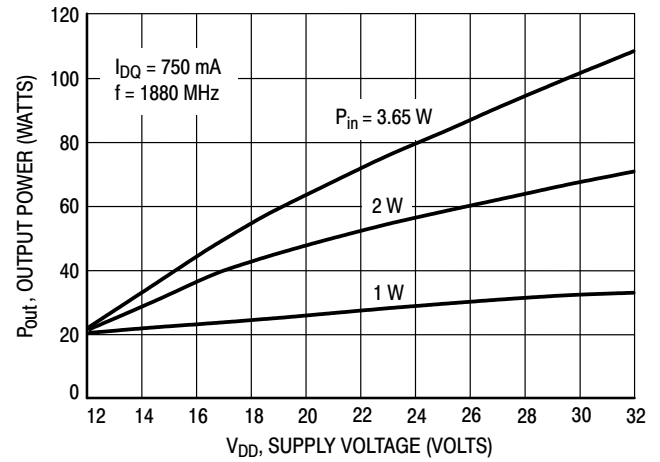


Figure 6. Output Power versus Supply Voltage

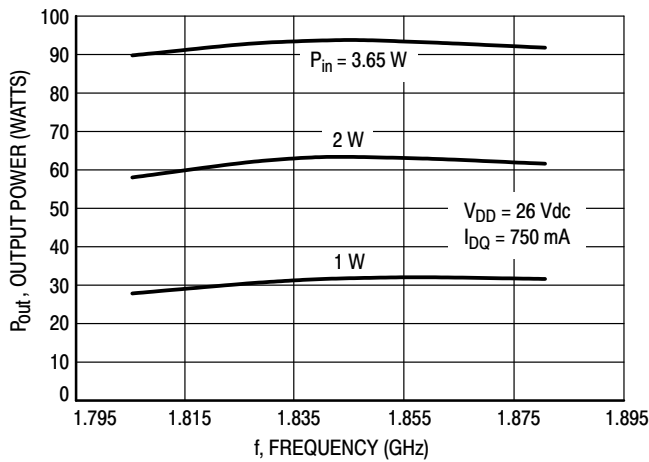


Figure 7. Output Power versus Frequency

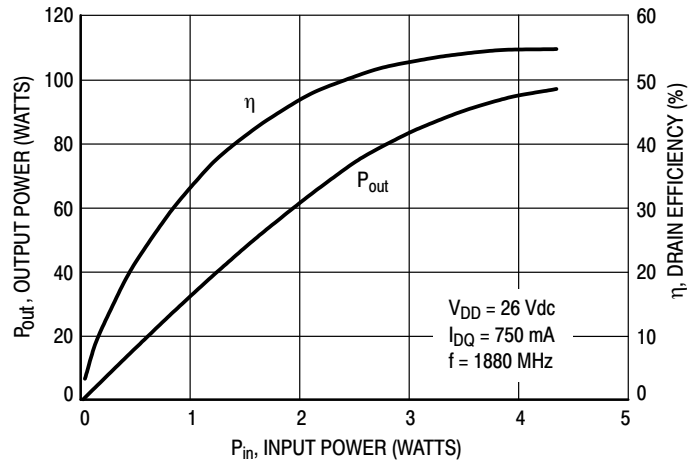


Figure 8. Output Power and Efficiency versus Input Power

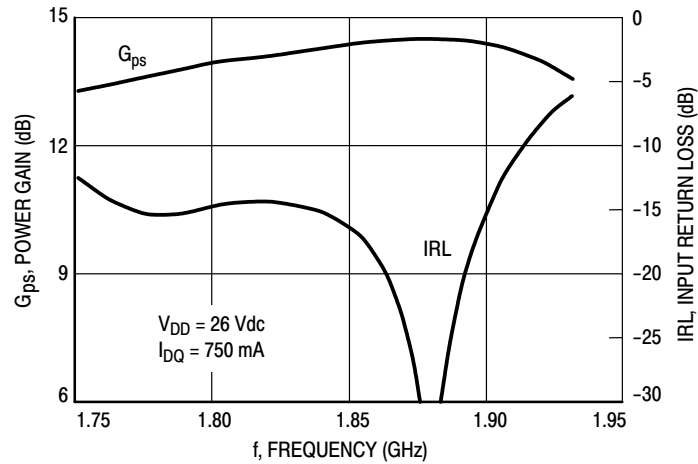
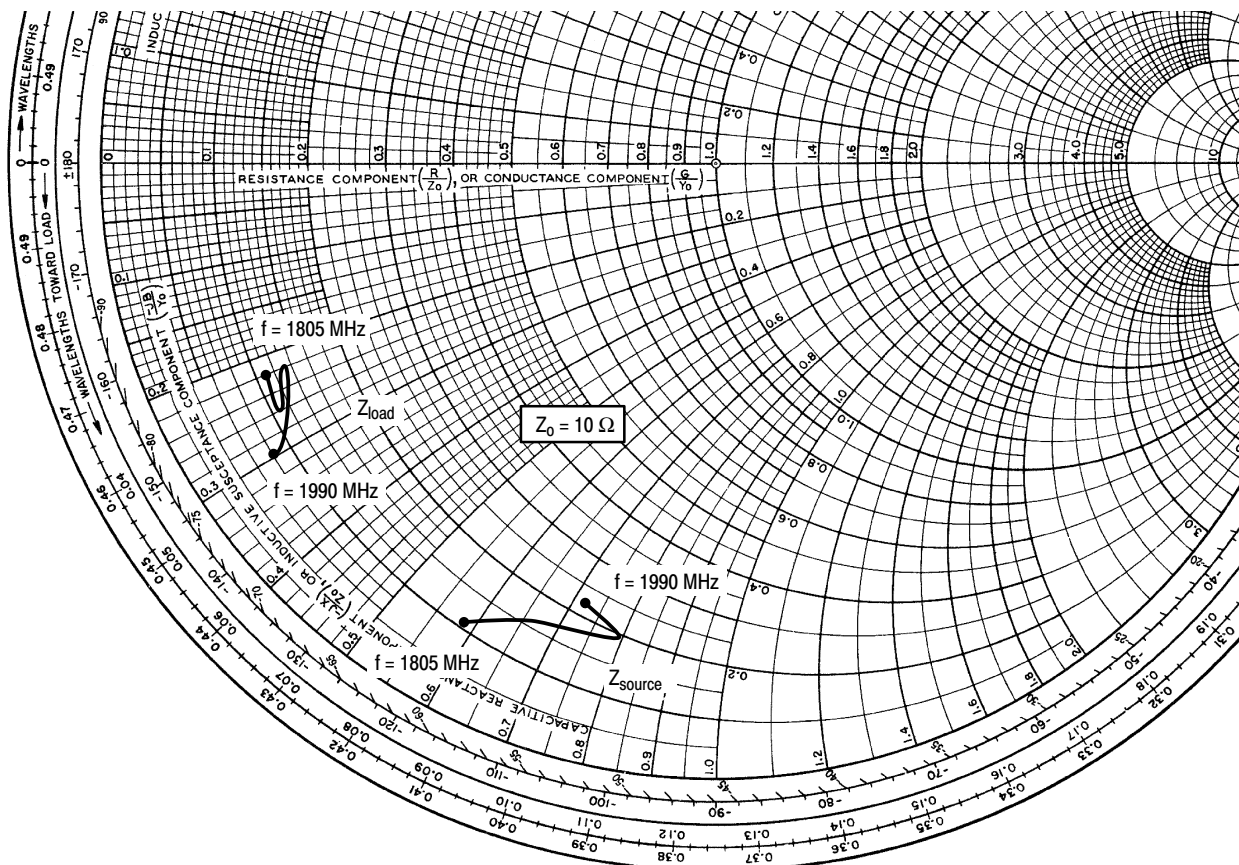


Figure 9. Wideband Gain and IRL (at Small Signal)



$V_{DD} = 26 \text{ V}$, $I_{DQ} = 750 \text{ mA}$, $P_{out} = 90 \text{ Watts (CW)}$

f MHz	Z_{source} Ω	Z_{load} Ω
1805	$1.10 - j5.85$	$1.15 - j2.16$
1880	$1.56 - j6.75$	$1.13 - j2.60$
1930	$2.05 - j8.00$	$1.30 - j2.23$
1990	$2.30 - j7.30$	$0.82 - j2.90$

Z_{source} = Test circuit impedance as measured from gate to ground.

Z_{load} = Test circuit impedance as measured from drain to ground.

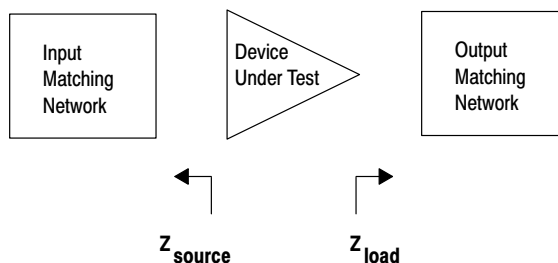
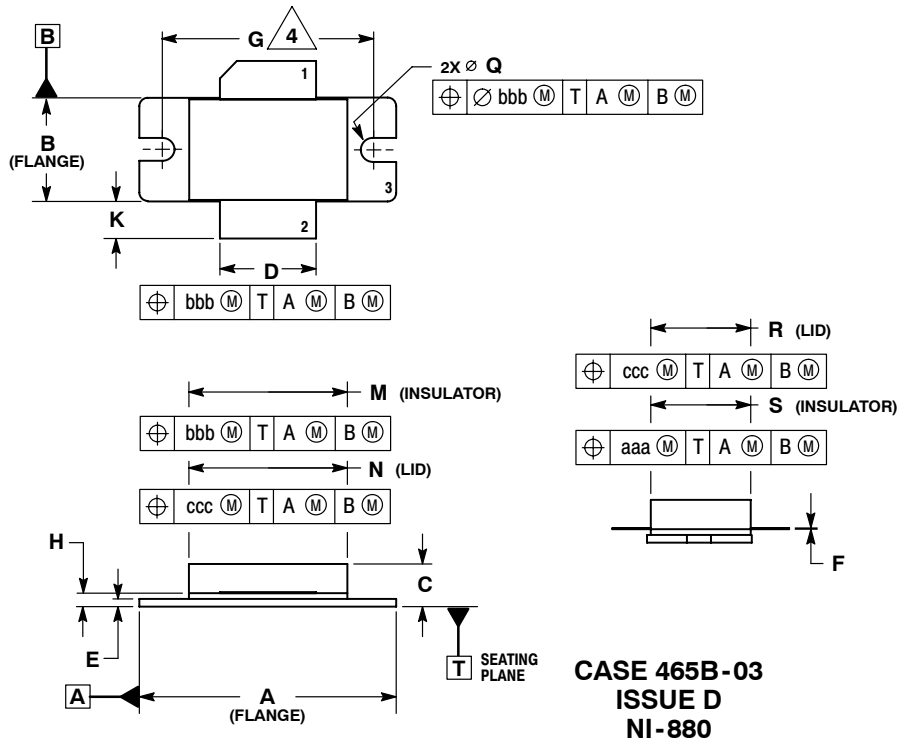


Figure 10. Large Signal Source and Load Impedance

PACKAGE DIMENSIONS



NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DIMENSION H IS MEASURED 0.030 (0.762) AWAY FROM PACKAGE BODY.
4. RECOMMENDED BOLT CENTER DIMENSION OF 1.16 (29.57) BASED ON M3 SCREW.

DIM	INCHES		MILLIMETERS	
	MIN	MAX	MIN	MAX
A	1.335	1.345	33.91	34.16
B	0.535	0.545	13.6	13.8
C	0.147	0.200	3.73	5.08
D	0.495	0.505	12.57	12.83
E	0.035	0.045	0.89	1.14
F	0.003	0.006	0.08	0.15
G	1.100 BSC		27.94 BSC	
H	0.057	0.067	1.45	1.70
K	0.175	0.205	4.44	5.21
M	0.872	0.888	22.15	22.55
N	0.871	0.889	19.30	22.60
Q	Ø.118	Ø.138	Ø3.00	Ø3.51
R	0.515	0.525	13.10	13.30
S	0.515	0.525	13.10	13.30
aaa	0.007 REF		0.178 REF	
bbb	0.010 REF		0.254 REF	
ccc	0.015 REF		0.381 REF	

STYLE 1:

1. DRAIN
2. GATE
3. SOURCE

How to Reach Us:

Home Page:

www.freescale.com

E-mail:

support@freescale.com

USA/Europe or Locations Not Listed:

Freescale Semiconductor
Technical Information Center, CH370
1300 N. Alma School Road
Chandler, Arizona 85224
+1-800-521-6274 or +1-480-768-2130
support@freescale.com

Europe, Middle East, and Africa:

Freescale Halbleiter Deutschland GmbH
Technical Information Center
Schatzbogen 7
81829 Muenchen, Germany
+44 1296 380 456 (English)
+46 8 52200080 (English)
+49 89 92103 559 (German)
+33 1 69 35 48 48 (French)
support@freescale.com

Japan:

Freescale Semiconductor Japan Ltd.
Headquarters
ARCO Tower 15F
1-8-1, Shimo-Meguro, Meguro-ku,
Tokyo 153-0064
Japan
0120 191014 or +81 3 5437 9125
support.japan@freescale.com

Asia/Pacific:

Freescale Semiconductor Hong Kong Ltd.
Technical Information Center
2 Dai King Street
Tai Po Industrial Estate
Tai Po, N.T., Hong Kong
+800 2666 8080
support.asia@freescale.com

For Literature Requests Only:

Freescale Semiconductor Literature Distribution Center
P.O. Box 5405
Denver, Colorado 80217
1-800-441-2447 or 303-675-2140
Fax: 303-675-2150
LDCForFreescaleSemiconductor@hibbertgroup.com

Information in this document is provided solely to enable system and software implementers to use Freescale Semiconductor products. There are no express or implied copyright licenses granted hereunder to design or fabricate any integrated circuits or integrated circuits based on the information in this document.

Freescale Semiconductor reserves the right to make changes without further notice to any products herein. Freescale Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does Freescale Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation consequential or incidental damages. "Typical" parameters that may be provided in Freescale Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals", must be validated for each customer application by customer's technical experts. Freescale Semiconductor does not convey any license under its patent rights nor the rights of others. Freescale Semiconductor products are not designed, intended, or authorized for use as components in systems intended for surgical implant into the body, or other applications intended to support or sustain life, or for any other application in which the failure of the Freescale Semiconductor product could create a situation where personal injury or death may occur. Should Buyer purchase or use Freescale Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold Freescale Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that Freescale Semiconductor was negligent regarding the design or manufacture of the part.

Freescale™ and the Freescale logo are trademarks of Freescale Semiconductor, Inc. All other product or service names are the property of their respective owners.
© Freescale Semiconductor, Inc. 2006. All rights reserved.

